



SOT1652-2

FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 1.92 mm body

16 September 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA780
Package type industry code	FBGA780
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-01-2016
Manufacturer package code	98ASA00899D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	23	-	mm
package width	-	23	-	mm
seated height	-	1.92	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	780	-	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: FCPBGA, NO LID, 23 X 23 X 1.92 PKG, 0.8 MM PITCH, 780 I/O	DOCUMENT NO: 98ASA00899D	REV: A	
	STANDARD: NON-JEDEC		
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Figure 2. Package outline note FBGA780 (SOT1652-2)

3 Legal information

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